IN THE CLAIMS

Please amend the claims as follows.

1. (Original) A method of manufacturing an optoelectronic package having an insulating base with multiple conductive vias running through the insulating base, and having a metal cover that at least partially encloses an optoelectronic device mounted on the insulating base, the method comprising:

placing a solder preform between the metal cover and the insulating base;

applying pressure between the metal cover and the insulating base; and

applying a current through the multiple conductive vias to heat the solder preform to melt.

2. (Original) The method of claim 1 further comprising:

metalizing a top surface of the insulating base prior to the placing of the solder preform.

3. (Previously Presented) The method of claim 2, further comprising:

allowing the solder preform to cool; and

removing the pressure between the metal cover and the insulating base.

4. (Original) The method of claim 1, further comprising:

allowing the solder preform to cool; and

removing the pressure between the metal cover and the insulating base.

5. (Original) A method of manufacturing a TO can comprising:

placing a solder preform between a metal cover and an insulating base; and

applying a current to the solder preform until the solder preform melts to seal a metal cover to the insulating base.

6. (Original) The method of claim 5, wherein the current is applied through conductive vias running through the insulating base.

7. (Original) The method of claim 5, further comprising:

creating a metallized surface on the insulating base, wherein placing the solder preform between the metal cover and the insulating base further comprises placing the solder preform in contact with the metallized surface.

8. (New) A method of manufacturing an optoelectronic package having an insulating base with multiple conductive vias running through the insulating base, and having a metal cover with a transparent portion that at least partially encloses an optoelectronic device mounted on the insulating base, the method comprising:

aligning the transparent portion with a beam emergence side of an optoelectronic device;

placing a solder preform between the metal cover and the insulating base;

applying pressure between the metal cover and the insulating base; and

applying a current through the multiple conductive vias to heat the solder preform to melt.

9. (New) The method of claim 8 further comprising:

metalizing a top surface of the insulating base prior to the placing of the solder preform.

10. (New) The method of claim 8, further comprising:

allowing the solder preform to cool; and

removing the pressure between the metal cover and the insulating base.

11. (New) The method of claim 8, further comprising:

allowing the solder preform to cool; and

removing the pressure between the metal cover and the insulating base.